Michael I. Gosselin

Contact Information	3540 Middlefield Road Menlo Park, CA, 94025	Mobile: +1-650-276-8473 E-mail: mike.gosselin88@gmail.com
Skills	 Mechanical Harware Skills: SolidWorks, exact-constraint design, DFA/DFM, estimation, focused & comprehensive physical prototyping (testing techniques, hand-construction) Electronic Harware Skills: Multilayer PCB design, fabrication & assembly (through hole & surface mount); Circui prototyping (point-to-point, breadboard, deadbug, & others); PCB re-work; microcon trollers [STM32F4, ATmega32u4]; LTSpice; KiCAD; Test & Measurement equipment (i.e oscilloscope); Mixed-signal circuit design; Analog filters & signal conditioning 	
	Software/Firmware Skills: • Git, Linux, Python/Numpy, C (on embedded devices), MATLAB, Simulink, LATEX	
PROFESSIONAL Transcriptic, Inc., Menlo Park, CA		
Experience	Hardware Team	August 2014 to Present
	• Collaborated with a team of six engineers to design and build three 5m x 2m x 1m Cartesian robots from raw components for automatic transport & handling of containers in biological experiments (all ME, EE, Firmware in-house).	
	• Held a role in the team as the responsible engineer for EE. Generated documentation for communicating EE-design information with team members (schematics, specification tables, assembly documentation).	
	 Interfaced with MEs on key design intersections: PCBA and connector positions & clearances, cable routing, motor selection. Special biological environmental sensor-device sub-project: collaborated with a Tran- 	
	scriptic firmware engineer to elicit needs, develop requirements, prototype circuits & firmware (parallel development), design final PCBA, design & execute tests.	
Relevant	DAC Project Menlo Park, CA	
Projects	Independent Project: "mStereo"	January 2013 - Present
	 Conceptualized, prototyped and tested a high-performance stereo audio DAC for use with personal computers. (Match industry best-in-class perfomance, undercut cost). Used LTSpice model and simulations to isolate the analog filter and output buffer subsystem: used to predict performance charateristics and make component selections. Used physical prototyping (solderless breadboards and SMD breakout-boards) to create a comprehensive physical prototype (full-system-integration validation). Used Solidworks to design an aluminum enclosure for electrical safety and to support panel connectors and controls. Fabrication (machining, press-in fasteners) outsourced. Created schematic, laid out 4-layer circuit board with surface mount components, and prepared maufacturing files (BOM, pick-and-place lists, Gerber files, stackup list). 	
Education	University of Pennsylvania, Philadelphia, PA, USA	
	Master of Science in Engineering, Mechanical E Specialization in Mechatronics	Engineering and Applied Mechanics December 2013
	University of British Columbia, Vancouver, BC, Canada	
	Bachelor of Applied Science, Mechanical Engin Engineering Co-op Program	meering May 2011
CITIZENSHIP	Canadian	
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